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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant Srinivasan Chakravarthi, et al. Docket Number: TI-33161.1

Serial No.: 10/677,610 Art Unit: 2818

Filed: 10/02/03 Examiner: Phuc T. Dang

For: Fabrication of Abrupt Ultra-Shallow Junctions

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NAME OF INVENTOR(S): Srinivasan Chakravarthi, et al.	
TITLE OF INVENTION: Fabrication of Abrupt Ultra-Shallow Junctions	
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